

# **Product Change Notification / ASER-13NQXI432**

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Date:							
16-Feb-2022							
<b>Product Category:</b>							
Memory							
PCN Type:							
Manufacturing Change							
Notification Subject:							
CCB 4686 Final Notice: Qualification of Ag on lead Die Attach Paddle (DAP) surface plating for selected SST25xxx and USBF4100Txxx device families available in 8L UDFN (2x3x0.55mm) package.							
Affected CPNs:							
ASER-13NQXI432_Affected_0 ASER-13NQXI432_Affected_0							
Notification Text:							
PCN Status:Final Notification							
PCN Type:Manufacturing Cha	nge						
Microchip Parts Affected:Plea Note: For your convenience N	•						
<b>Description of Change</b> :Qualific SST25xxx and USBF4100Txxx of							
Pre and Post Change Summa	ry:						
	Pre Change	Post Change					

Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-1) LTD. (NSEB)				
Wire Material	Au	Au				
Die Attach Material	HR-5104	HR-5104				
Molding Compound Material	G700LTD	G700LTD				
	EFTEC-64T	EFTEC-64T				
Lead-Frame Material	See Pre and Post Change Summary for					
	comparison.					
DAP Surface Prep	Pd custom plating	Ag on lead only				

### Impacts to Data Sheet:None

Change ImpactNone

**Reason for Change:**To improve productivity by qualifying Ag on lead Die Attach Paddle (DAP) surface plating

**Change Implementation Status:**In Progress

Estimated First Ship Date:March 31, 2022 (date code: 2214)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

# Time Table Summary:

	May 2021			>	February 2022			March 2022							
Workweek	1 9	2	2 1	2 2	2		0 6	0 7	0 8	0 9	10	11	12	13	14
Initial PCN Issue Date			Х												
Qual Report Availability									Х						
Final PCN Issue Date									Х						
Estimated Implementation Date															Х

Method to Identify Change: Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**May 17, 2021: Issued initial notification.

February 16, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on March 31, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachments:

PCN\_ASER-13NQXI432\_Pre and Post Change Summary.pdf PCN\_ASER-13NQXI432 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

SST25PF040CT-40E/NP

SST25PF040CT-40E/NP-125

SST25PF040CT-40I/NP

SST25PF040CT-40I/NP18GVAO

SST25PF040CT-40V/NP

SST25PF040CT-40V/NP18GVAO

SST25WF020AT-40I/NP

USBF4100T-I/NP

USBF4100T-I/NPVAO

USBF4100T-V/NP

USBF4100T-V/NPVAO

Date: Tuesday, February 15, 2022